



DESCRIPTION

$V_{DS}=60V$

$V_{GS}=\pm 20V$

$ID(A)=3.3A$

$R_{DS(ON)}= 67m\Omega(\text{Typ.}) @ V_{GS}= 10V$

$R_{DS(ON)}= 76m\Omega(\text{Typ.}) @ V_{GS}= 4.5V$

AM2308 is available in a SOT-23S package.

FEATURES

- Fast Switch
- Available in a SOT-23S package.

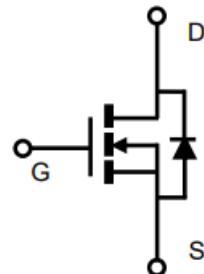
ORDERING INFORMATION

Package Type	Part Number	
SOT-23S SPQ: 3,000pcs/Reel	E3S	AM2308E3SR
		AM2308E3SVR
Note	V: Halogen free Package R: Tape & Reel	
AiT provides all RoHS products		

APPLICATION

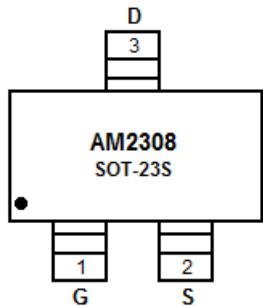
- Head-Held Instruments
- Power Management
- LED Lighting

N CHANNEL MOSFET





PIN DESCRIPTION



Top View

Pin #	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain



ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted

V_{DSS} , Drain-Source Voltage	60V	
V_{GSS} , Gate-Source Voltage	$\pm 20\text{V}$	
I_D , Continuous Drain Current	$T_A=25^\circ\text{C}$	3.3A
	$T_A=70^\circ\text{C}$	3.0A
I_{DM} , Pulsed Drain Current ^{NOTE2}	13.4A	
I_{AS} , Avalanche Current ^{NOTE2}	5A	
E_{AS} , Single Pulse Avalanche Energy ($L=0.3\text{mH}$) ^{NOTE2}	3.75mJ	
P_D , Power Dissipation ^{NOTE1}	$T_A=25^\circ\text{C}$	1.6W
	$T_A=70^\circ\text{C}$	1W
T_J , Operation Junction Temperature	$-55^\circ\text{C} \sim 150^\circ\text{C}$	
T_{STG} , Storage Temperature Range	$-55^\circ\text{C} \sim 150^\circ\text{C}$	

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Surface mounted on FR4 board using 1 in² pad size

NOTE2: Pulsed width limited by maximum junction temperature, $T_{J(MAX)}=150^\circ\text{C}$ (initial temperature $T_J=25^\circ\text{C}$).

NOTE3: Using $\leq 10\text{s}$ junction-to-ambient thermal resistance is base on $T_{J(MAX)}=150^\circ\text{C}$.

THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction to Ambient ^{NOTE1}	$R_{\theta JA}$	-	80	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient ^{NOTE1, 3}		-	130	



ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Conditions	Min	Typ.	Max	Units
Static Parameters						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=250\mu\text{A}$	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}, T_J=75^\circ\text{C}$	-	-	10	
Gate Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=250\mu\text{A}$	1.2	1.9	2.5	V
Drain-Source On-state Resistance ^{NOTE4}	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.3\text{A}$	-	67	80	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=2.3\text{A}$	-	76	90	
Forward Transconductance	G_{fs}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=3.3\text{A}$	-	6.2	-	S
Diode Characteristics						
Diode Forward Voltage ^{NOTE4}	V_{SD}	$I_{\text{SD}}=1\text{A}, V_{\text{GS}}=0\text{V}$	-	0.75	1	V
Diode Continuous Forward Current	I_{s}		-	-	1.7	A
Dynamic and Switching Parameter^{NOTE5}						
Total Gate Charge(10V)	Q_{g}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{DS}}=3.3\text{A}$	-	6.6	9.8	nC
Total Gate Charge(4.5V)	Q_{g}		-	3.2	4.8	
Gate-Source Charge	Q_{gs}		-	1.4	2.1	
Gate-Drain Charge	Q_{gd}		-	1.0	1.5	
Input Capacitance	C_{iss}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	426	-	pF
Output Capacitance	C_{oss}		-	35	-	
Reverse Transfer Capacitance	C_{rss}		-	14	-	
Turn-on Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=30\text{V}, V_{\text{GEN}}=10\text{V}, R_{\text{G}}=3.3\Omega, I_{\text{D}}=1\text{A},$	-	4.5	8.0	ns
	t_{r}		-	8.0	15	
Turn-off Time	$t_{\text{d}(\text{off})}$		-	14	25	
	t_{f}		-	5.0	9.0	

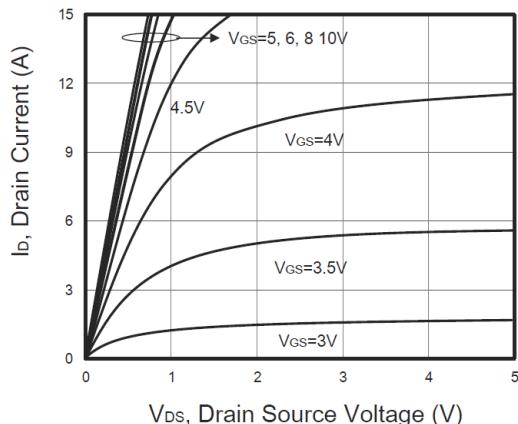
NOTE4: Pulse test width $\leq 300\mu\text{s}$ and duty cycle $\leq 2\%$.

NOTE5: Guaranteed by design, not subject to production testing.

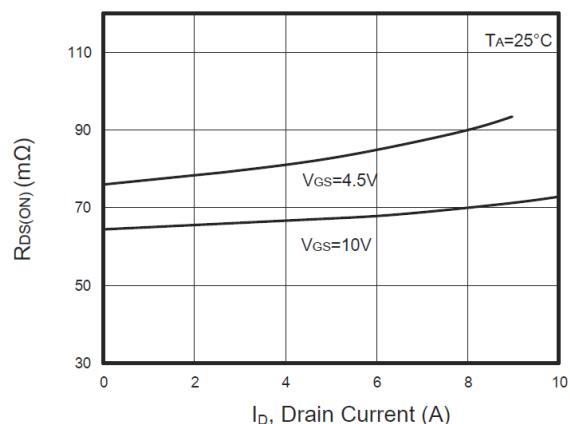


TYPICAL CHARACTERISTICS

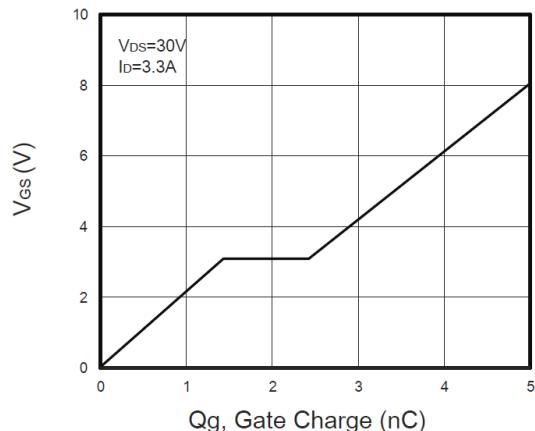
1. Output Characteristics



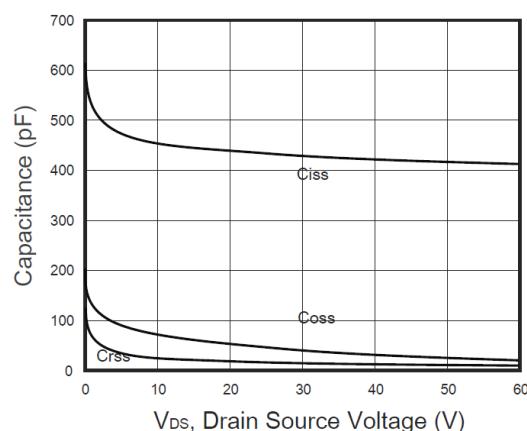
2. Drain-Source On Resistance



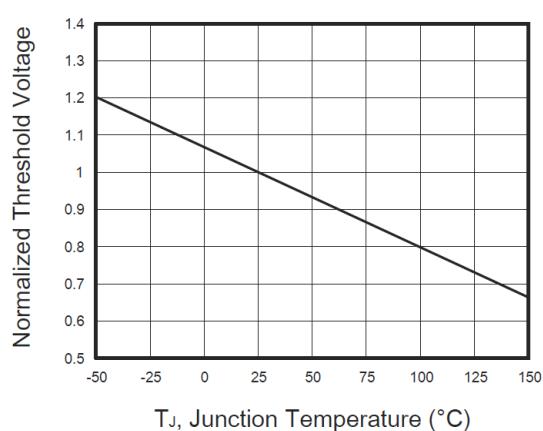
3. Gate Charge



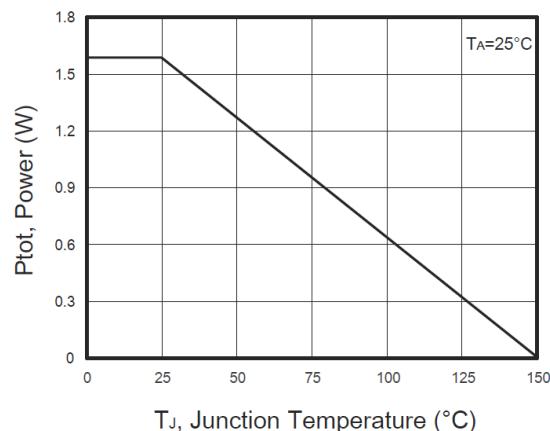
4. Capacitance



5. Gate Threshold Voltage

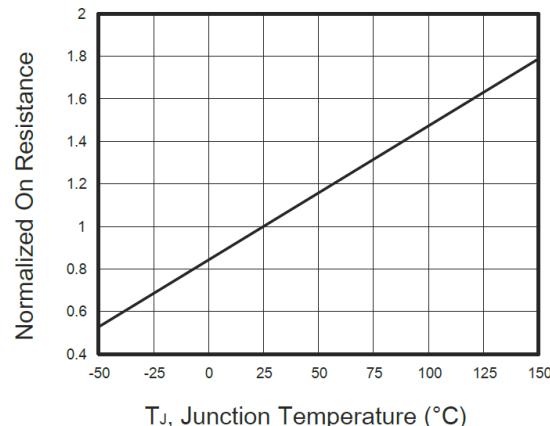


6. Power Dissipation

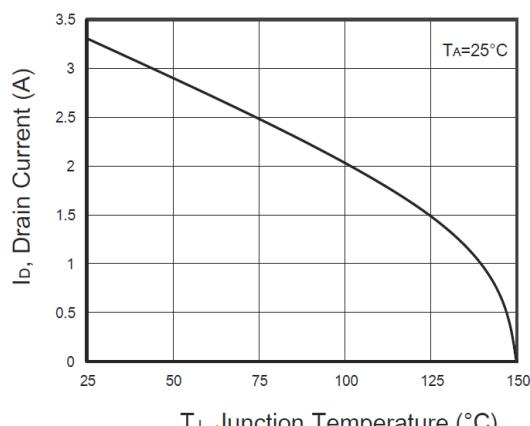




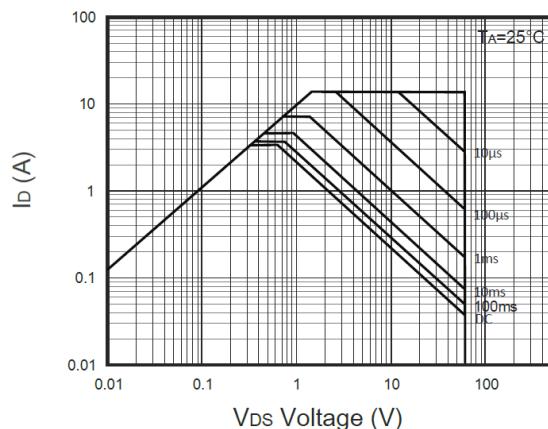
7. Drain-Source On Resistance



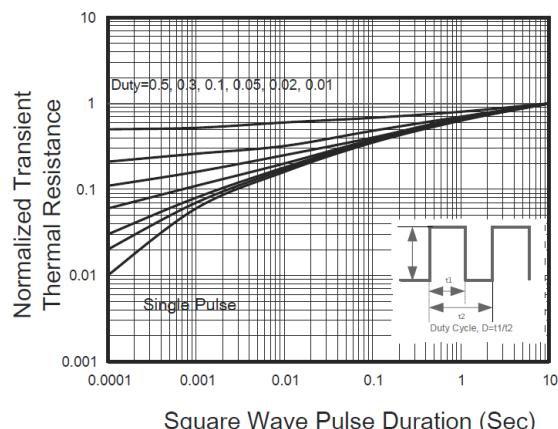
8. Drain Current vs T_J



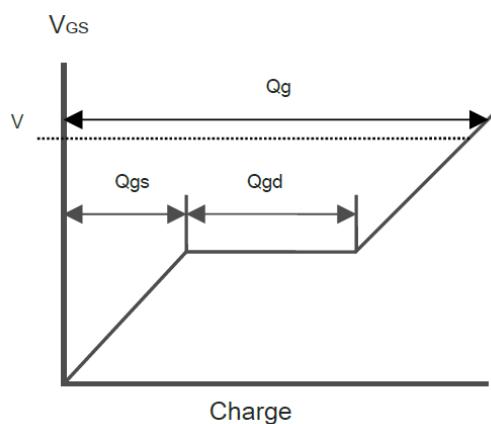
9. Maximum Safe Operation Area



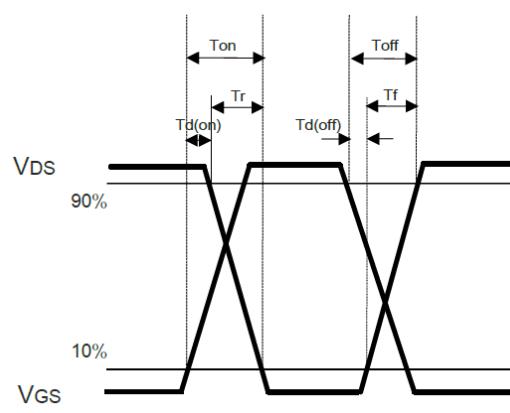
10. Thermal Transient Impedance



11. Gate Charge Waveform



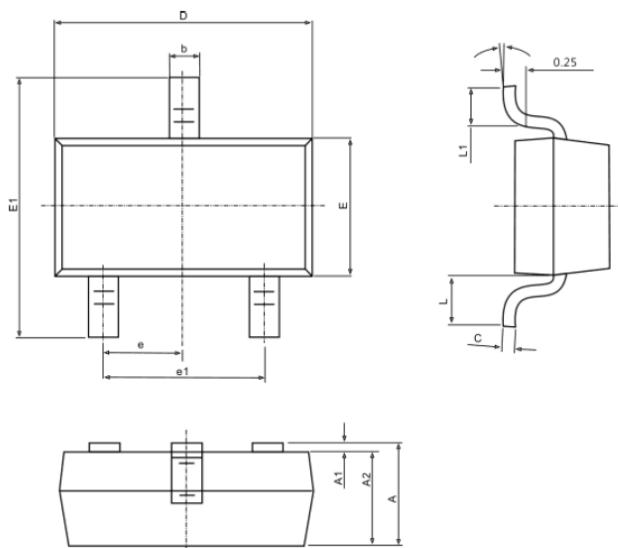
12. Switching Time Waveform



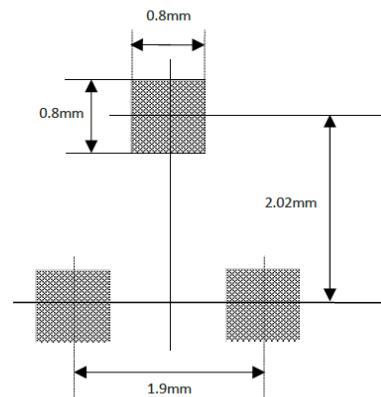


PACKAGE INFORMATION

Dimension in SOT-23S Package (Unit: mm)



Recommended Land Pattern



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.940	1.120	0.037	0.044
A1	0.040	0.120	0.002	0.005
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.004	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 BSC		0.037 BSC	
e1	1.800	2.000	0.071	0.079
L	0.500	0.600	0.020	0.024
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°



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